

Heatsinks f.cool

- ▶ Profile heatsinks and fluid coolers
- ▶ Heatsinks and active heatsinks for processors
- ▶ Board Level heatsinks
- ▶ Cooling aggregates
- ▼ Accessories for electronic components
  - ▼ Thermal conductive material
    - Silicone rubber insulating material for semiconductors
    - Thermally conductive foil made of siliconelastomer
    - Silicone-free thermal conductive foils
    - High thermoconducting graphite foils
    - Thermal conductive foil one-sided adhesive
    - Thermally conductive foil both sides adhesive
    - Heat conductive foam and gel foils
    - Kapton insulator washers
    - [Mica wafers](#)
    - Aluminium oxide wafers
    - Thermal conductive paste and thermal interface film
    - Thermally conductive adhesive
  - ▶ Fixing material for mechanical components
  - ▶ Mounting material for single semiconductors and heatsinks

Cases f.case

Connectors f.con

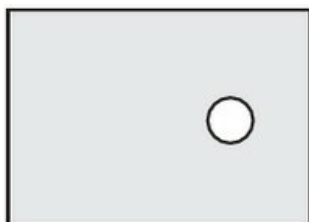
Mica wafers

GS 66 P

TO 66, 18 x 13,5 mm, customer specific versions on request

Data sheet

add to request



Features

Technical Drawing

Service

Accessories / related products

<b>for transistor material</b>	TO 66 muskovit
<b>material thickness</b>	0.05 mm
<b>thermal resistance (GS 3)</b>	0.4 K/W
<b>dielectric strength</b>	5 kV
<b>insulation resistance</b>	$3 \cdot 10^{17} \Omega \cdot \text{cm}$